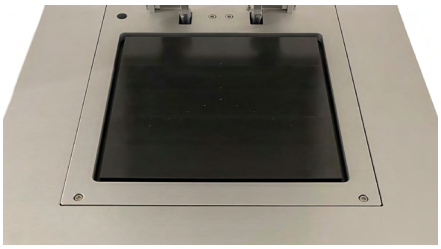
SAWATEC
SWISS HIGHTECH SYSTEMS

COOLPLATE CP-200

Short process time due to controlled cooling



Wafer Clean & Primer	Photoresist & Soft Bake	Mask Alignment & Exposure	Post Bake & Develop	Etch & Hard Bake	Stripping	Clean & Inspection
Spin Rinser Dryer Hotplates (Dehumidifier)	Spin Modules Spray Coater Hotplates		Hotplates **Coolplates** Developer	Developer Developer-Etch Hotplates	Developer-Etch	Spin Rinser Dryer



At SAWATEC you can get different **Coolplates** for fast and controlled cooling of flat substrates. The Coolplate series shortens the process time when cooling the substrates or wafers. If required, the cooling rate can be increased with a chiller.

The semi-automatic Coolplates impress with their high-quality design and easy handling. It can be used for substrates up to Ø 200 mm and thicknesses up to 14 mm or with wafers ranging in size from 50 x 50 to 200 x 200 mm, round or square.

Coolplates are available as mobile cabinet and bench-mounted unit.



FEATURES (BASIC CONFIGURATION)

- Digital temperature with actual value display
- User-friendly process configuration with touch screen
- Quick start/stop function for repeat processes
- Proximity/loading pins, can be easily adapted to different substrate sizes
- Manual substrate fixation via vacuum
- Manual loading and unloading of substrates



PERFORMANCE DATA

- Temperature range: 5 - 23 °C (temperature < 18 °C with chiller)
- Electrical driven proximity/loading pins
- Proximity adjustment from 0 - 1 mm (0.1 mm increments)
- Substrate size: max. 200 mm (round or square)
- Pin-circle-diameters: 45 - 192 mm (2 - 8“)

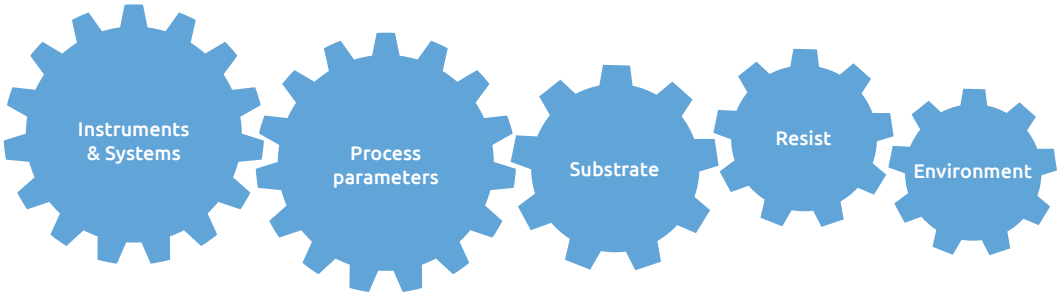
ADDITIONAL FUNCTIONS (OPTIONS)

- Setup tool for optimal height adjustment of the pins and leveling of the Coolplate
- Can be combined with a commercially available chiller for precise control of the cooling temperature or rather the cooling liquid.

INTERACTION OF THE PROCESS PARAMETERS

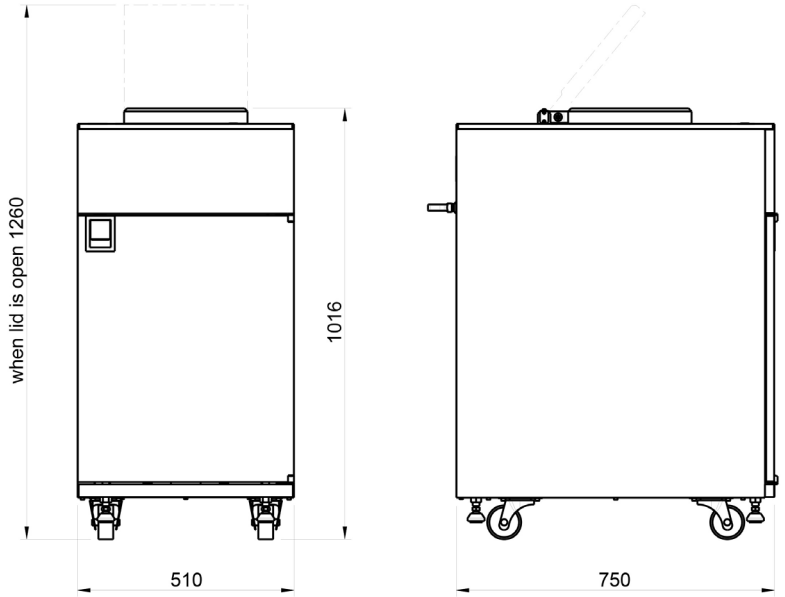
To ensure that a high level of process reliability can be reached, the interaction of our products with the defined process parameters, the selected substrate and the photoresist must be perfectly co-ordinated.

Furthermore, the process environment exerts a great influence on the process quality, therefore the ambient temperature, the exhaust and supply air (laminar flow) and all technical connections (N2, compressed air …) must be designed optimally.



DESIGN AND DIMENSIONS

- Compact, space-saving design
- Mobile cabinet made of electro polished stainless steel
- Colour touch screen
- Coolplate: 260 x 260 mm, anodised aluminium
- Lid: opening and closing with pneumatic stroke, anodized aluminum
- Proximity pins made of Inconel Ø 1 mm
- Dimensions Cabinet (lid open): 750 x 510 x 1260 mm (L x W x H)
- Dimensions BM (lid open): 595 x 380 x 480mm (L x W x H)
- Weight (Cab / BM) : approx. 87 kg / 44 kg

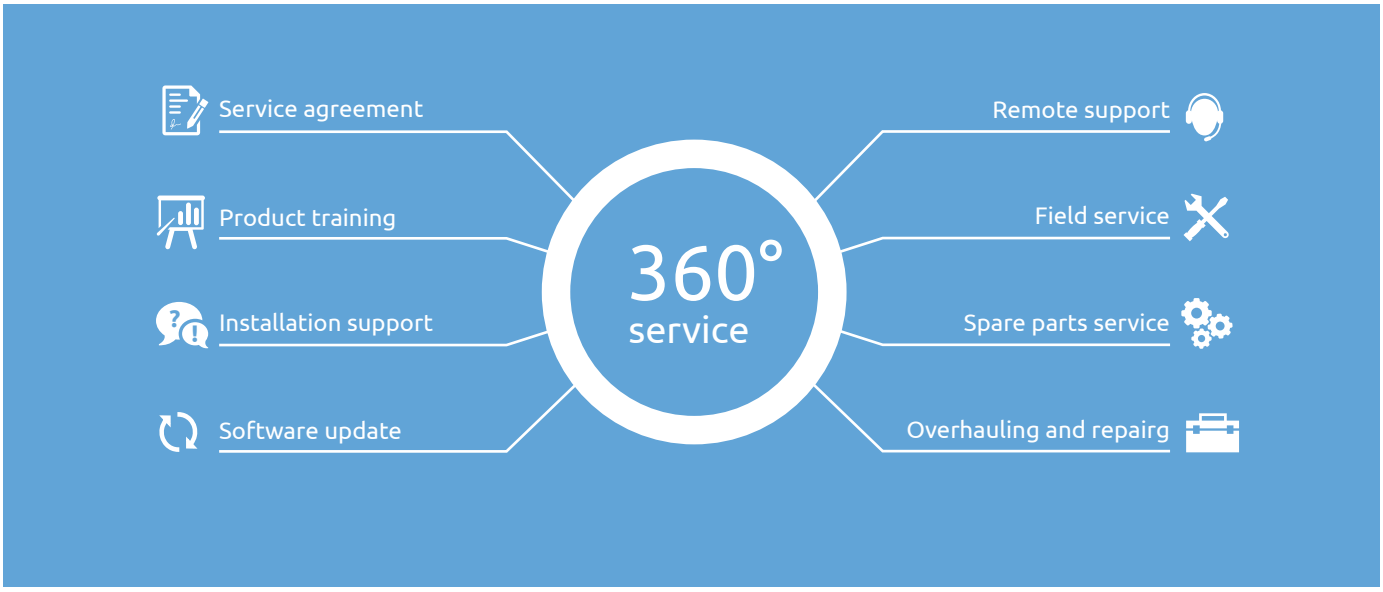


REQUIRED MEDIA

- Electrical connection: 230 VAC, 50/60 Hz
- Compressed air: 6 bar, tube Ø 6/4 mm
- Technical vacuum: -0.8 bar, tube Ø 6/4 mm
- Exhaust connector (BM / Cab): Ø 40 mm
- Water connection: inlet and outlet



SWISS QUALITY



If you would like a personal consultation or have a specific request, please do not hesitate to call us. Our technical experts will be pleased to help you.

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